

N-Channel Enhancement Mode Power MOSFET

Features:

- Low On Resistance
- Simple Drive Requirement
- Fast Switching Characteristic
- RoHS compliant package

Description :

The KWP13N50CE3 is a N-channel enhancement-mode MOSFET, providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness.

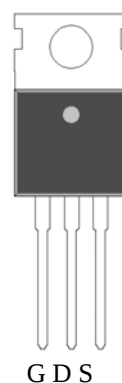
The TO-220 package is universally preferred for all commercial-industrial applications.

Applications :

- Adapter
- Switching Mode Power Supply

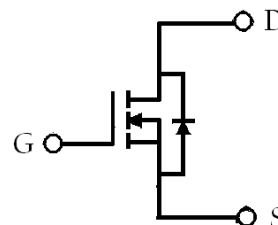
Outline

TO-220



Symbol

KWP13N50CE3



G : Gate D : Drain S : Source

BV_{DSS}	500V
I_D @ V_{GS}=10V, T_C=25°C	13A
I_D @ V_{GS}=10V, T_C=100°C	8.2A
R_{DS(ON)}@V_{GS}=10V, I_D=6.5A	0.42Ω (typ)

Ordering Information

Device	Package	Shipping
KWP13N50CE3	TO-220 (RoHS compliant package)	50 pcs/tube, 20 tubes/box, 4 boxes / carton

Absolute Maximum Ratings (T_C=25°C)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage (Note 1)	V _{DS}	500	V
Gate-Source Voltage	V _{GS}	±30	
Continuous Drain Current @T _C =25°C, V _{GS} =10V	I _D	13*	A
Continuous Drain Current @T _C =100°C, V _{GS} =10V		8.2*	
Pulsed Drain Current @ (Note 2)	I _{DM}	52*	
Single Pulse Avalanche Energy @ L=8mH, I _D =4Amps, V _{DD} =50V	E _{AS}	64	mJ
Single Pulse Avalanche Current (Note 2)	I _{AS}	4	A
Repetitive Avalanche Energy	E _{AR}	4.8	mJ
Maximum Temperature for Soldering @ Lead at 0.125 in(0.318mm) from case for 10 seconds	T _L	300	°C
Total Power Dissipation (T _C =25°C)	P _D	195	W
Linear Derating Factor		1.72	W/°C
Operating Junction and Storage Temperature	T _J , T _{stg}	-55~+150	°C

*Drain current limited by maximum junction temperature

*100% UIS testing in condition of V_{DD}=50V, L=8mH, V_G=10V, I_L=3A, Rated V_{DS}=500V

Note : 1. T_J=+25°C to +150°C.

2. Pulse width limited by maximum junction temperature.

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	R _{θJC}	0.64	°C/W
Thermal Resistance, Junction-to-ambient, max	R _{θJA}	62.5	

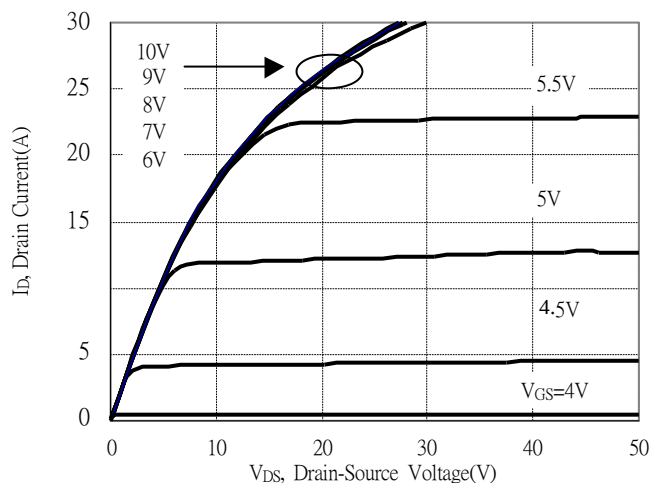
Characteristics (T_j=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	500	-	-	V	V _{GS} =0V, I _D =250μA
ΔBV _{DSS} /ΔT _j	-	0.6	-	V/°C	Reference to 25°C, I _D =250μA
V _{GS(th)}	2.0	-	4.0	V	V _{DS} = V _{GS} , I _D =250μA
*G _{FS}	-	15	-	S	V _{DS} =15V, I _D =6.5A
I _{GSS}	-	-	±100	nA	V _{GS} =±30V, V _{DS} =0V
I _{DSS}	-	-	1	μA	V _{DS} =500V, V _{GS} =0V
I _{DSS}	-	-	10		V _{DS} =400V, V _{GS} =0V, T _j =125°C
*R _{DS(ON)}	-	0.42	0.53	Ω	V _{GS} =10V, I _D =6.5A
Dynamic					
*Q _g	-	35.8	-	nC	I _D =13A, V _{DD} =250V, V _{GS} =10V
*Q _{gs}	-	7.6	-		
*Q _{gd}	-	10.8	-		
*t _{d(ON)}	-	17	-	ns	V _{DD} =250V, I _D =13A, V _{GS} =10V, R _G =9.1Ω
*t _r	-	16.8	-		
*t _{d(OFF)}	-	63.4	-		
*t _f	-	31.8	-		
C _{iss}	-	1479	-	pF	V _{GS} =0V, V _{DS} =25V, f=1MHz
C _{oss}	-	150	-		
C _{rss}	-	36	-		
Source-Drain Diode					
*I _S	-	-	13	A	
*I _{SM}	-	-	52		
*V _{SD}	-	0.79	1.2	V	I _S =6.5A, V _{GS} =0V
*t _{rr}	-	318	-	ns	V _{GS} =0V, I _F =13A, dI _F /dt=100A/μs
*Q _{rr}	-	3.02	-	μC	

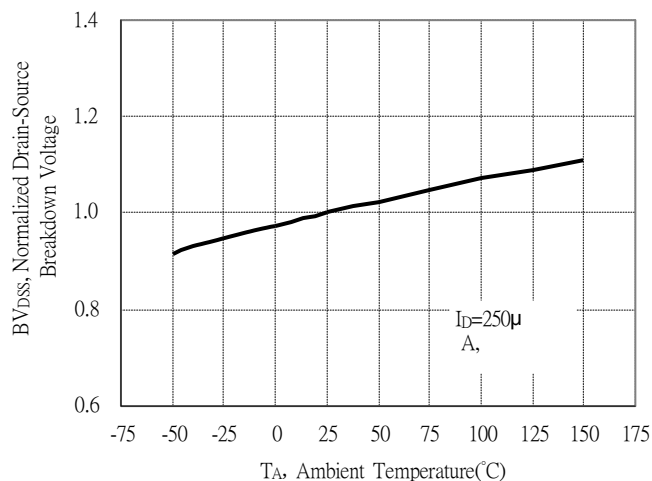
*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

Typical Characteristics

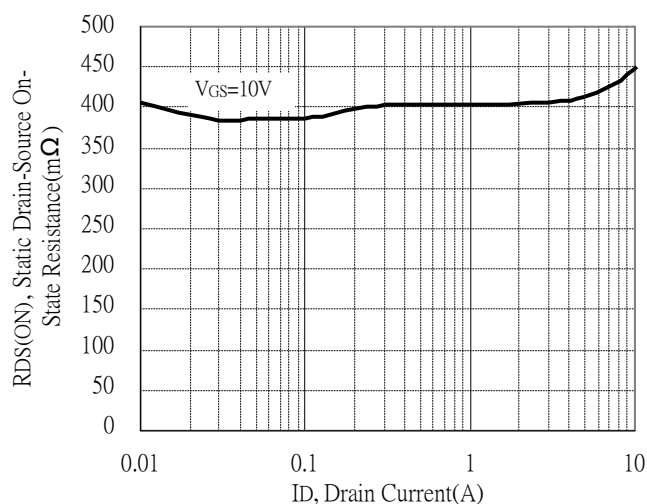
Typical Output Characteristics



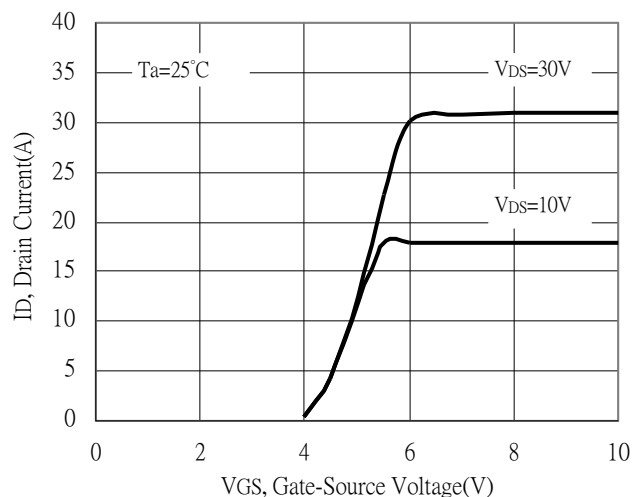
Breakdown Voltage vs Ambient Temperature



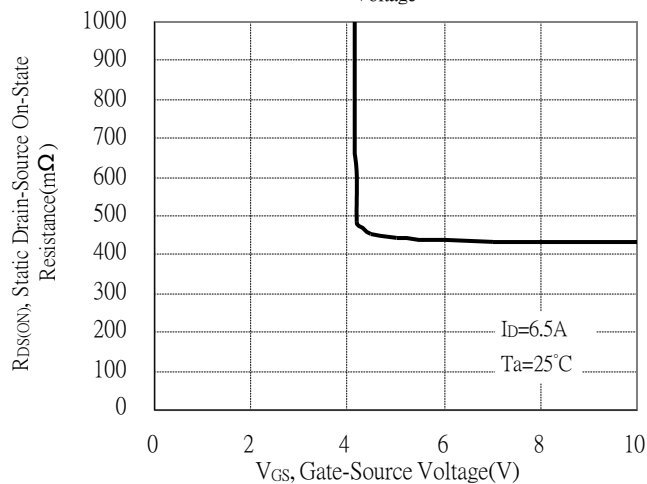
Static Drain-Source On-State resistance vs Drain Current



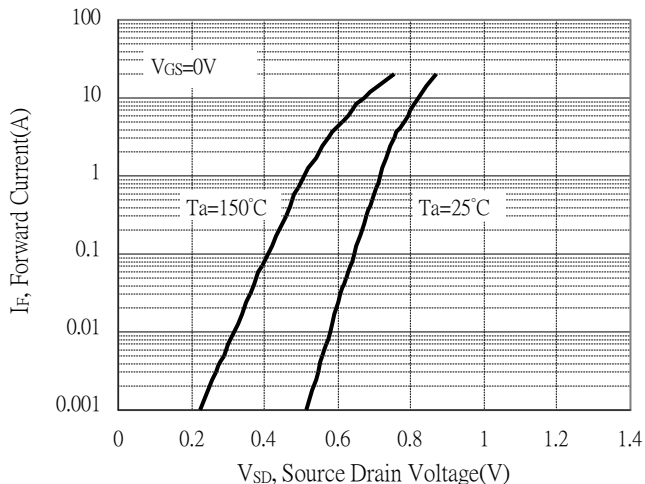
Drain Current vs Gate-Source Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

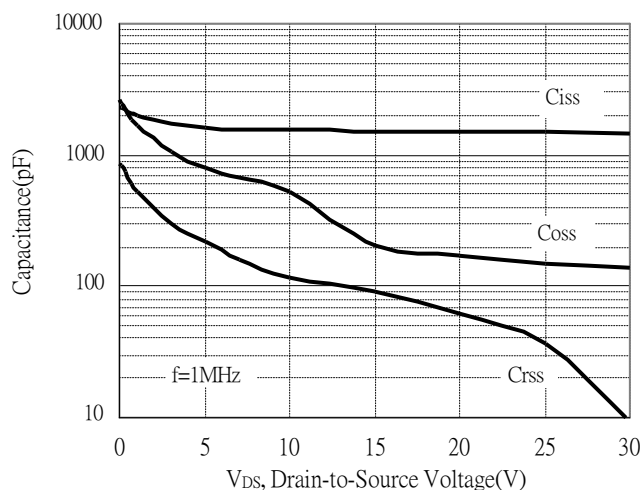


Forward Drain Current vs Source-Drain Voltage

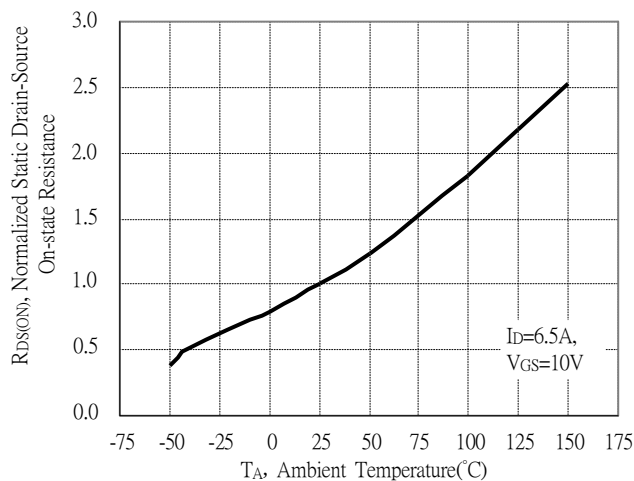


Typical Characteristics(Cont.)

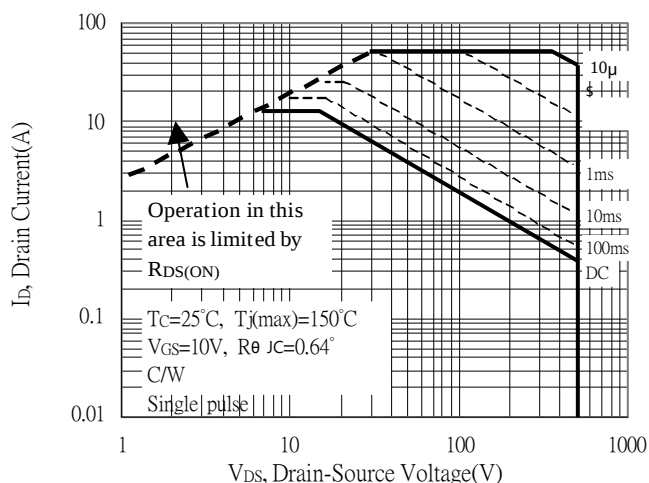
Capacitance vs Reverse Voltage



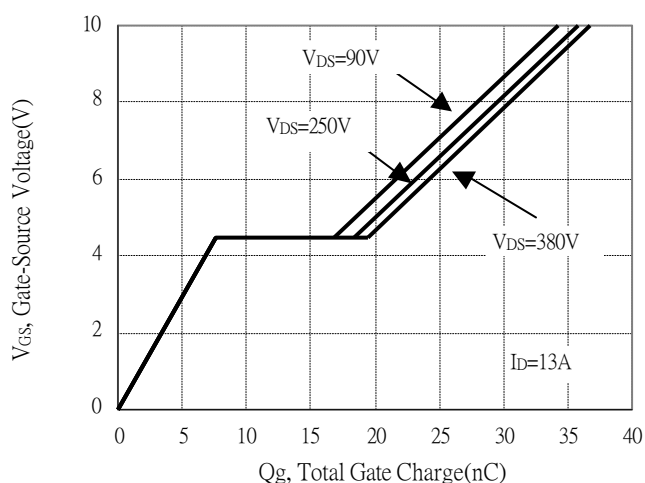
Static Drain-Source On-resistance vs Ambient Temperature



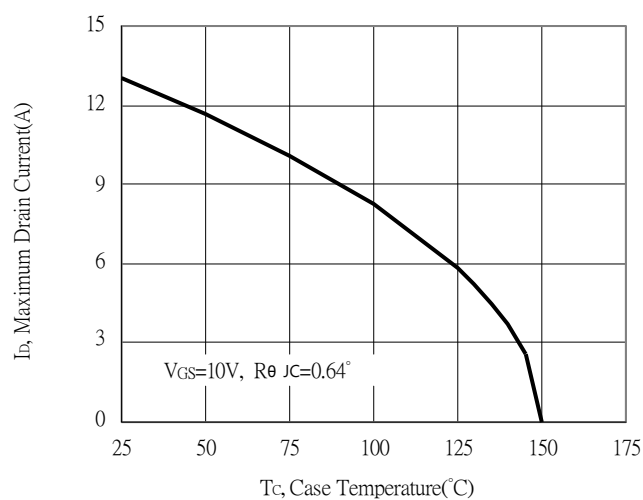
Maximum Safe Operating Area



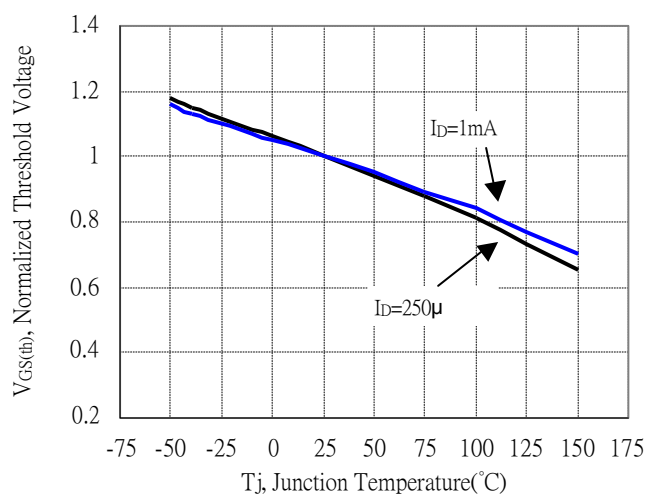
Gate Charge Characteristics



Maximum Drain Current vs Case Temperature

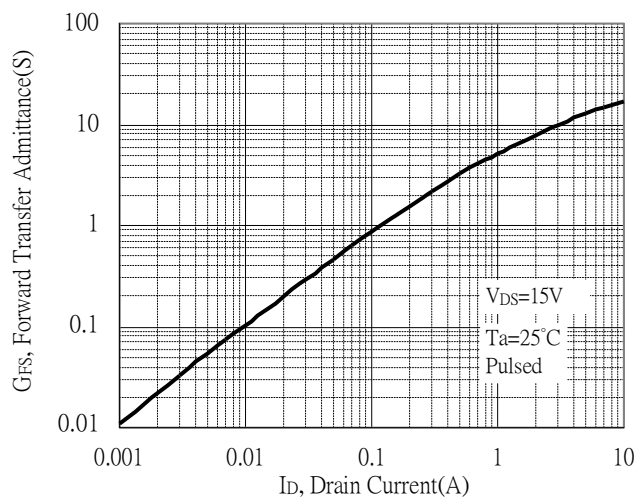


Threshold Voltage vs Junction Temperature

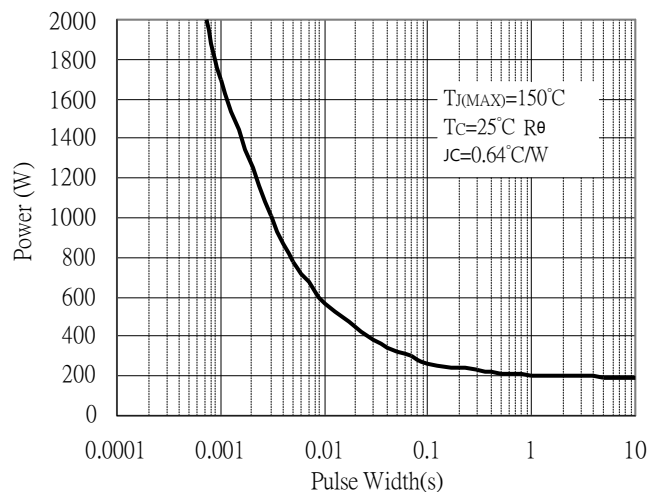


Typical Characteristics(Cont.)

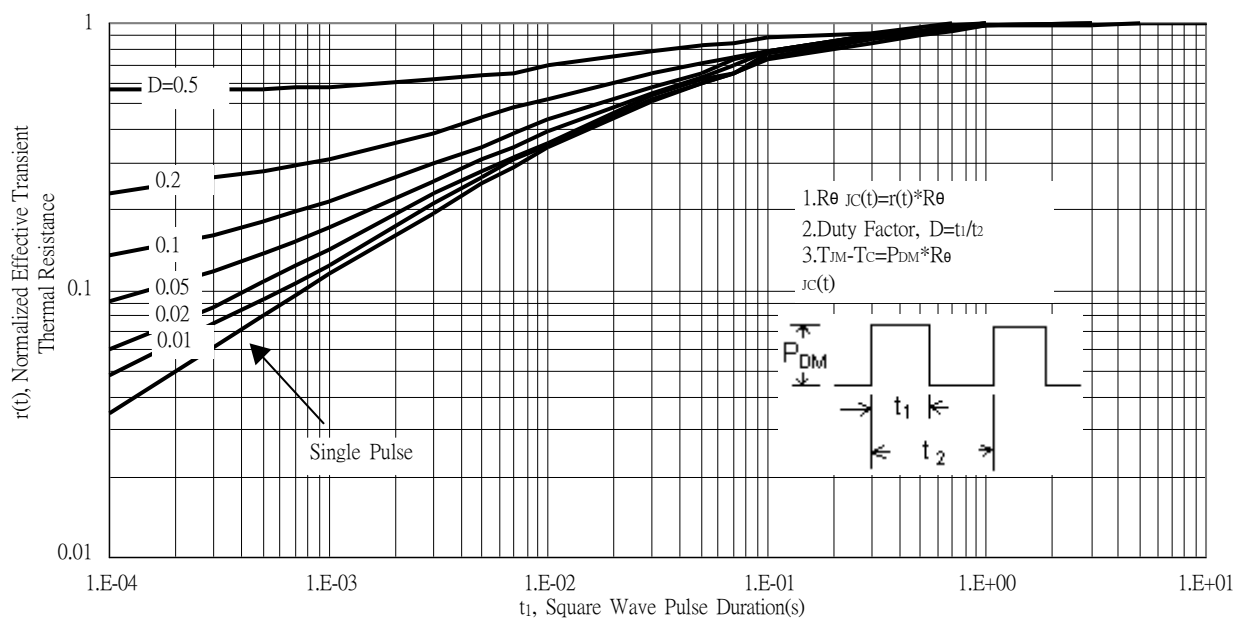
Forward Transfer Admittance vs Drain Current



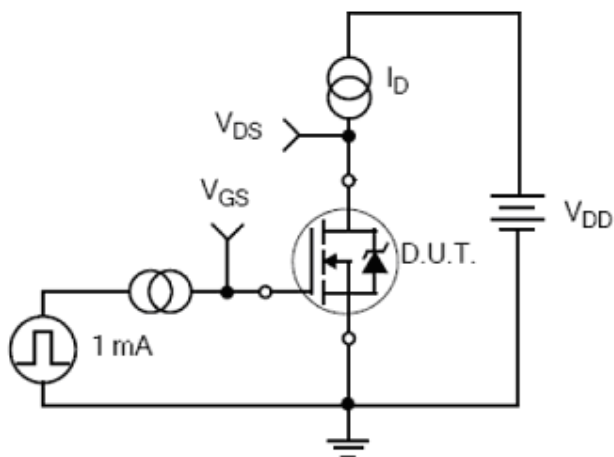
Single Pulse Power Rating, Junction to Case



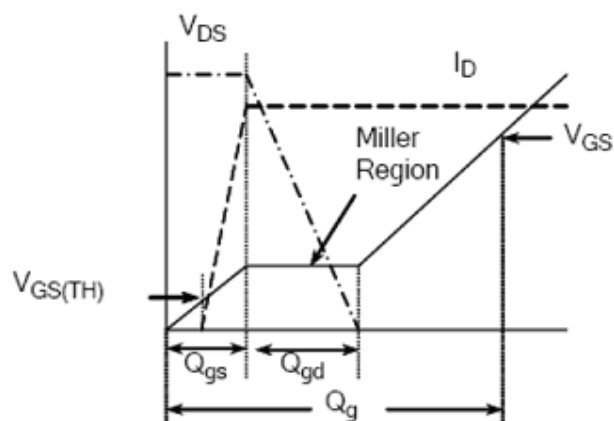
Transient Thermal Response Curves



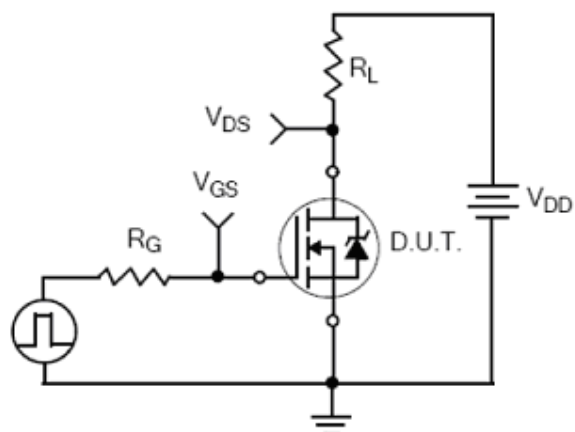
Test Circuit and Waveforms



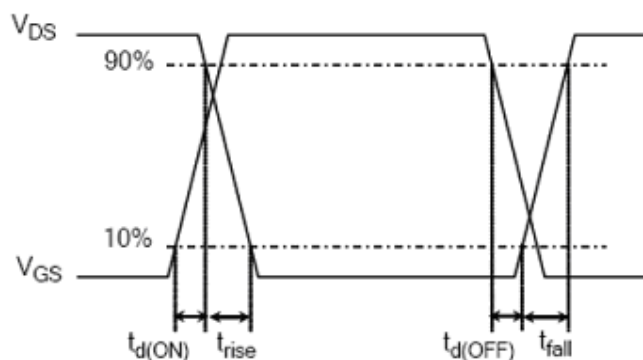
Gate Charge Test Circuit



Gate Charge Waveform

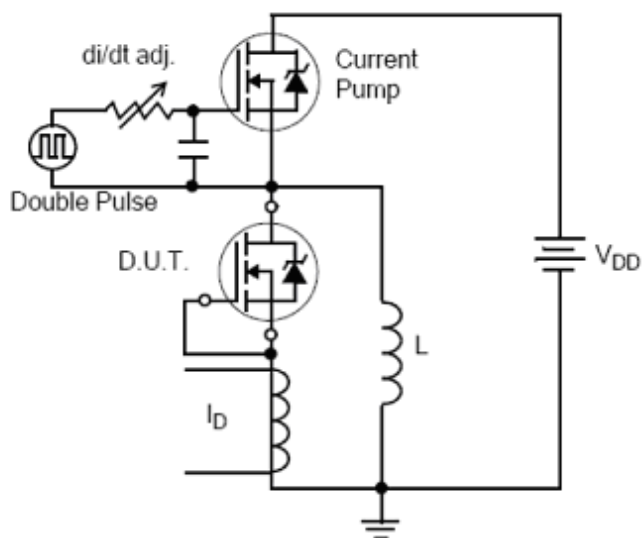


Resistive Switching Test Circuit

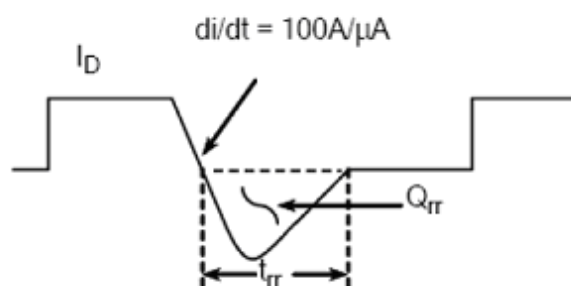


Resistive Switching Waveforms

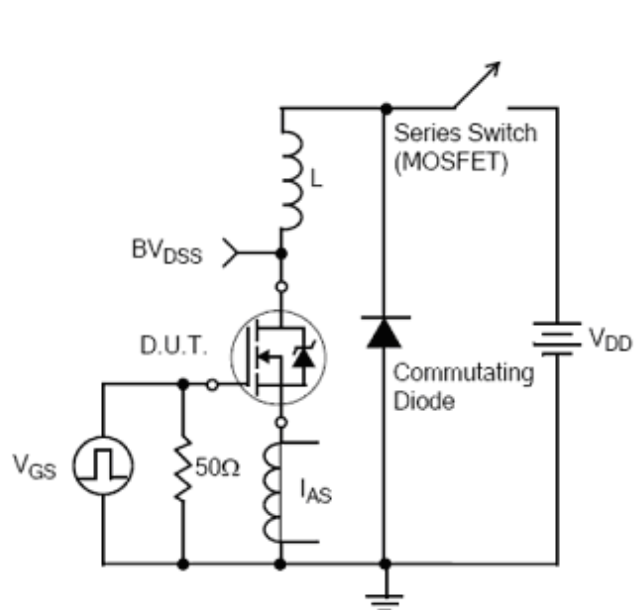
Test Circuit and Waveforms(Cont.)



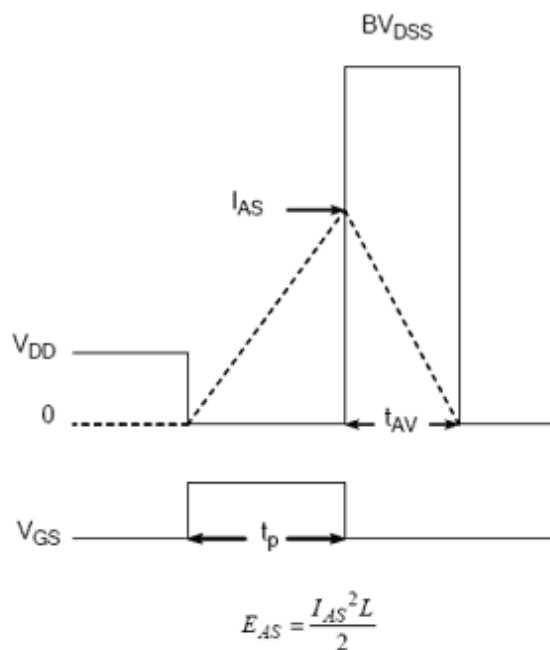
Diode Reverse Recovery Test Circuit



Diode Reverse Recovery Waveform

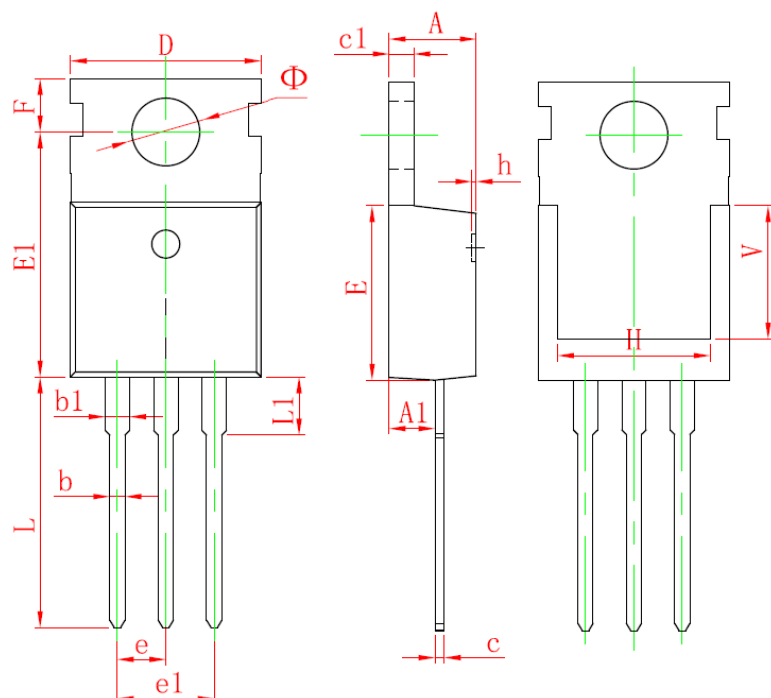


Unclamped Inductive Switching Test Circuit



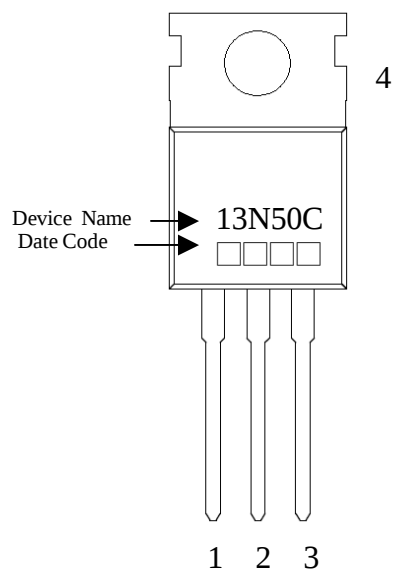
Unclamped Inductive Switching Waveforms

TO-220 Dimension



3-Lead TO-220 Plastic Package
 Package Code: E3

Marking:



Style: Pin 1.Gate 2.Drain 3.Source
 4.Drain

*: Typical

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181	e	2.540*		0.100*	
A1	2.250	2.550	0.089	0.100	e1	4.980	5.180	0.196	0.204
b	0.710	0.910	0.028	0.036	F	2.650	2.950	0.104	0.116
b1	1.170	1.370	0.046	0.054	H	7.900	8.100	0.311	0.319
c	0.330	0.650	0.013	0.026	h	0.000	0.300	0.000	0.012
c1	1.200	1.400	0.047	0.055	L	12.900	13.400	0.508	0.528
D	9.910	10.250	0.390	0.404	L1	2.850	3.250	0.112	0.128
E	8.950	9.750	0.352	0.384	V	7.500	REF	0.295	REF
E1	12.650	12.950	0.498	0.510	Φ	3.400	3.800	0.134	0.150